



Screen-Printed SHJ Solar Cells with Complex Silver Inks

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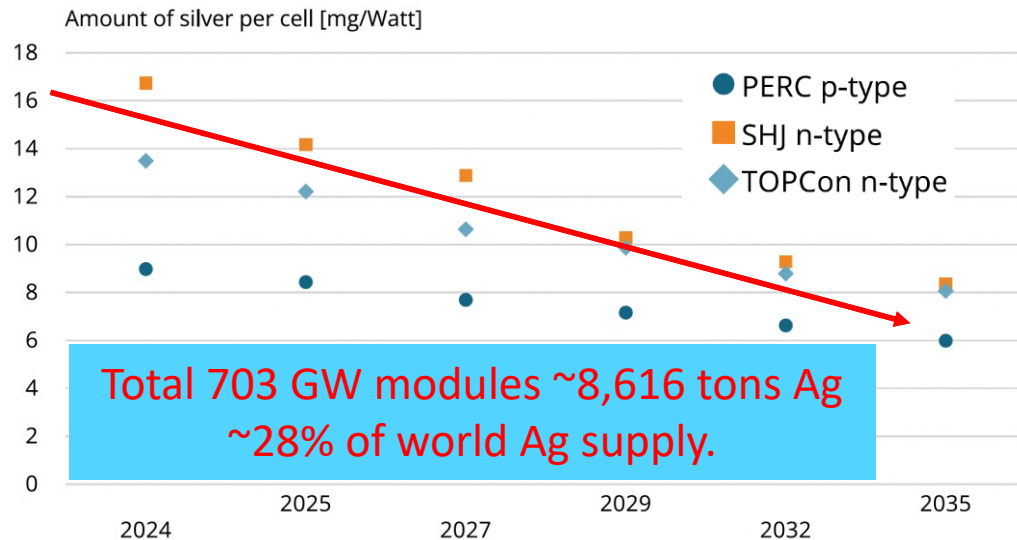
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- 4** Phase transition
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Motivation

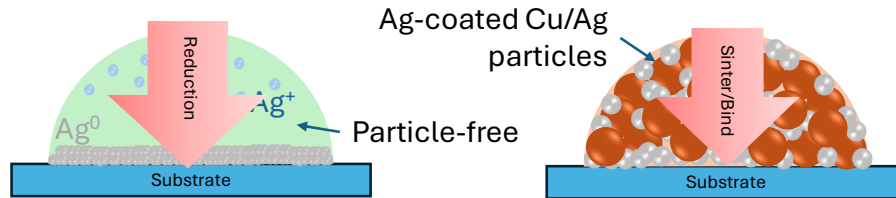
- SHJ cells: >20% world market share in the next decade.
- Record efficiency on SHJ-based cells: 27.81% [2].
- Drawback: **high Ag consumption** due to:
 - low-temperature processing (200C)
 - high resistivity metal paste.



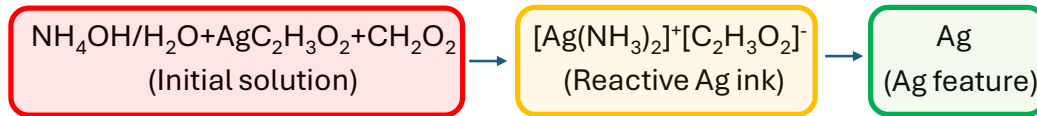
Reduce Ag usage!

Ag complex ink (reactive Ag ink)?

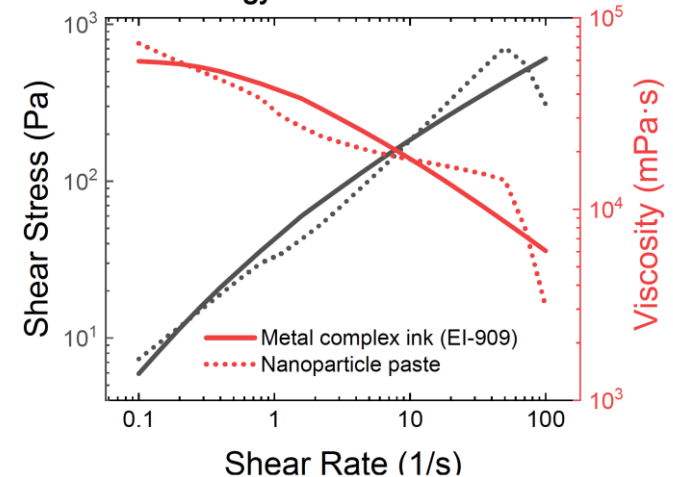
A: Metal complex ink vs. nanoparticle paste



B: Complex Ag ink reduction

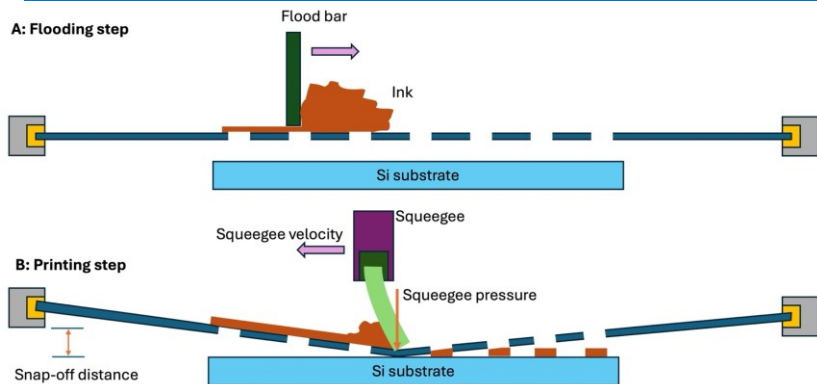


C: Rheology

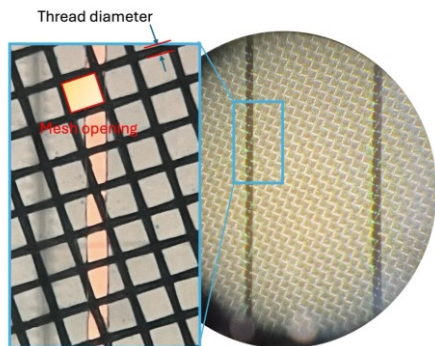


- Metal complex ink (or reactive ink): reduction. Nanoparticle paste: binding/sintering.
- Complex ink reduction: for a denser film, outgassing need to be prioritized.
- Rheology: **commercial product EI-909** has similar viscosity and thixotropy vs. nanoparticle paste.

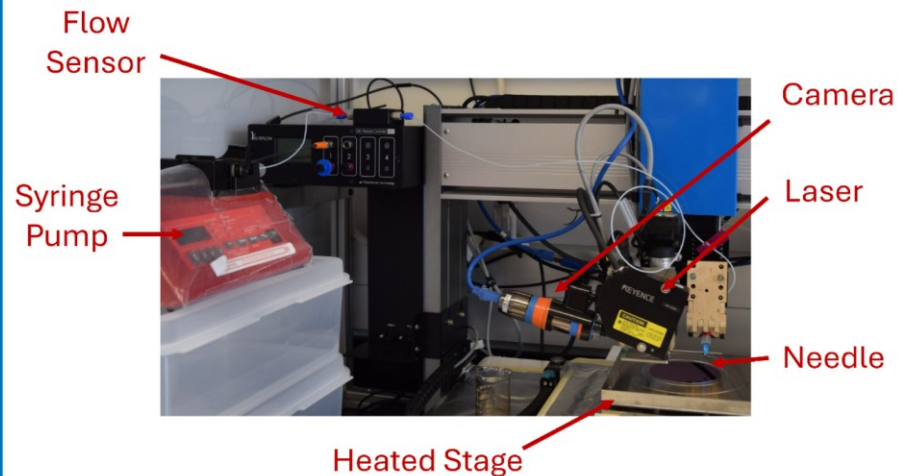
Printing technology for complex inks



C: Optical images of a screen



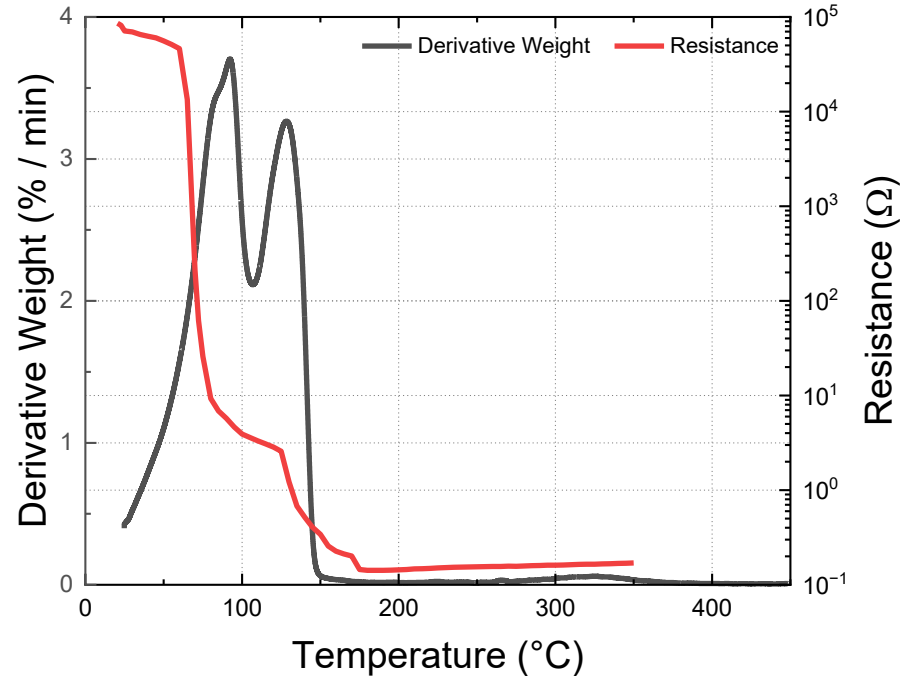
- Screen printing metallization: high throughput, dominant technology (>95% market share).
- This work: reactive ink + screen printing.



- Previous work on printing reactive inks: nozzle dispensing [2]. **Low throughput.**

Phase transition of Ag complex ink

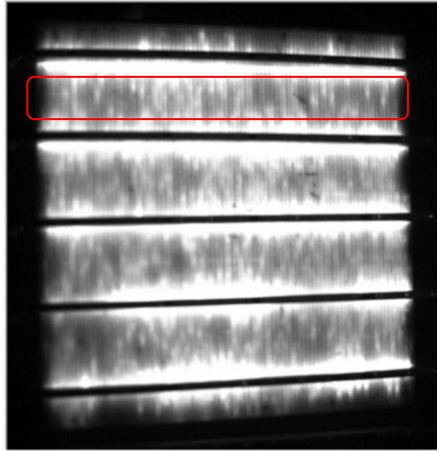
- Electroninks EI-909 Ag complex ink.
- TGA: two distinct phase transitions at 90C and 130C.
 - 90C: evaporation of NH_4OH components.
 - 130C: reduction of Ag ions to metallic Ag.
 - >150C: no more mass change.
- Resistance:
 - from 70C: resistance drops.
 - 130C additional decrease.
 - >175C: no further changes are observed. Fully reduced to Ag^0 .



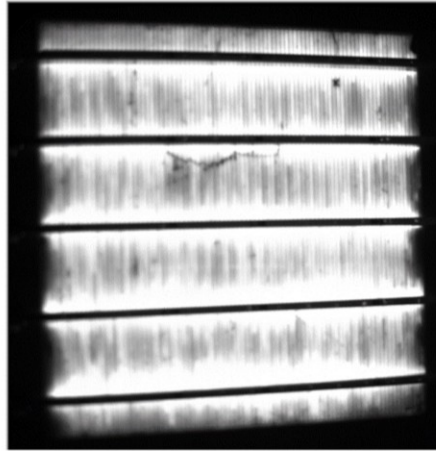
Complex ink printed cells
annealed at 180C for 30 min!

Electroluminescence images

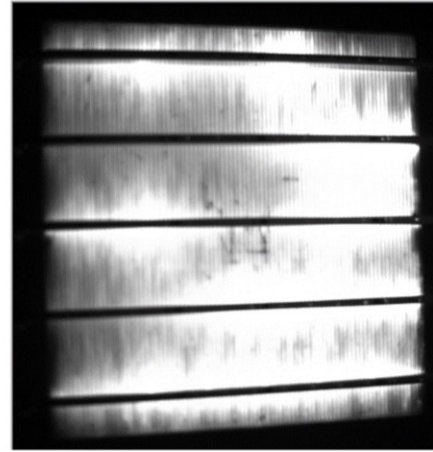
Single print



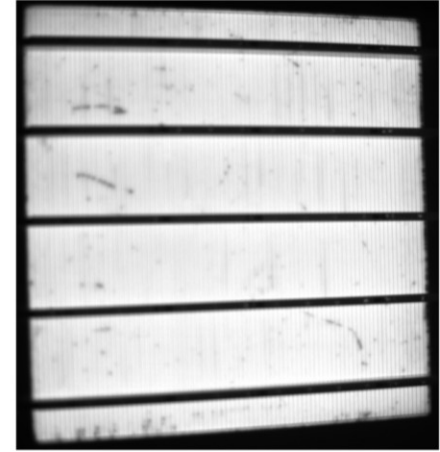
Double print



Triple print



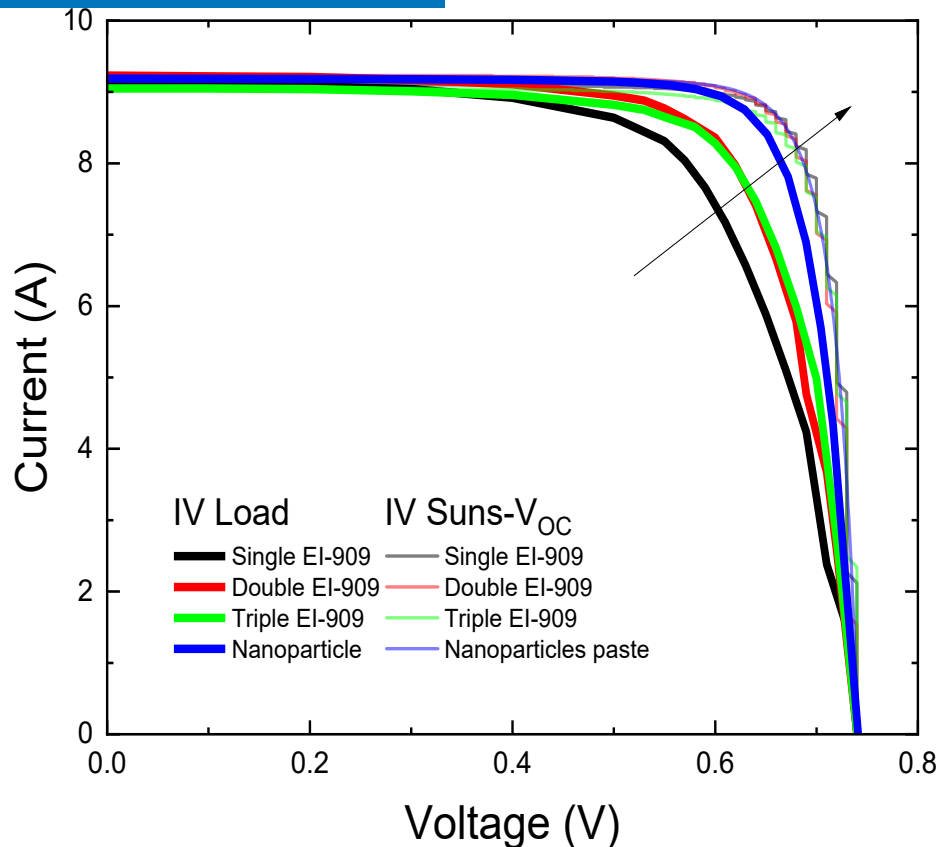
Single NP print



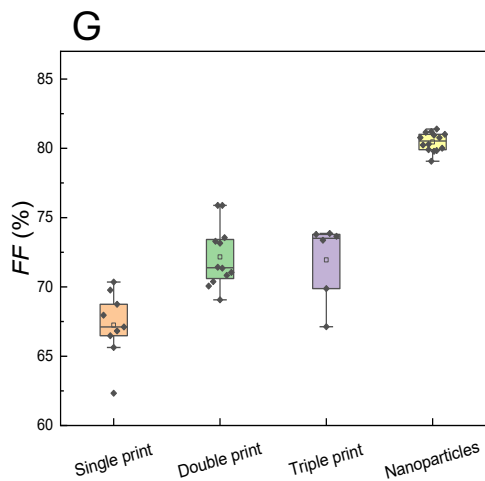
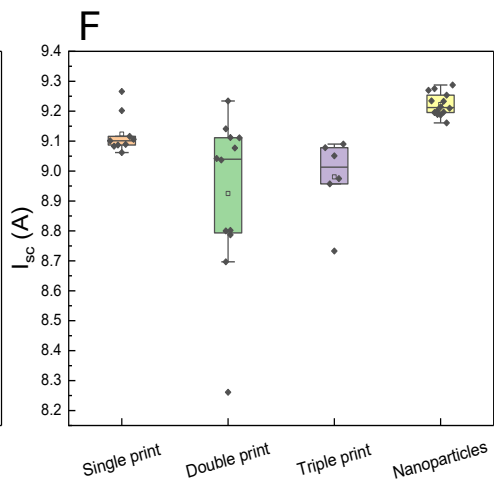
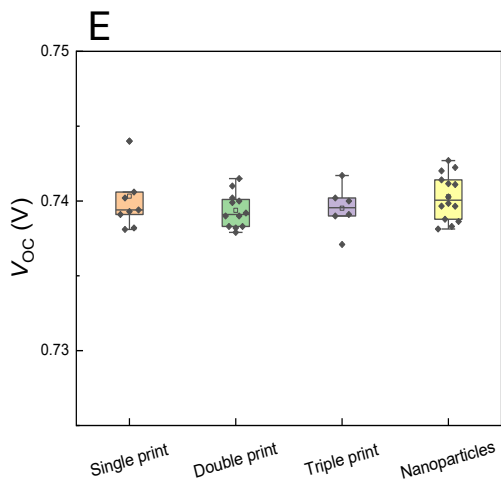
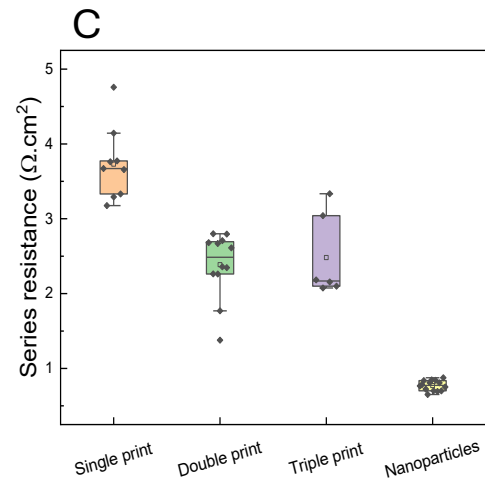
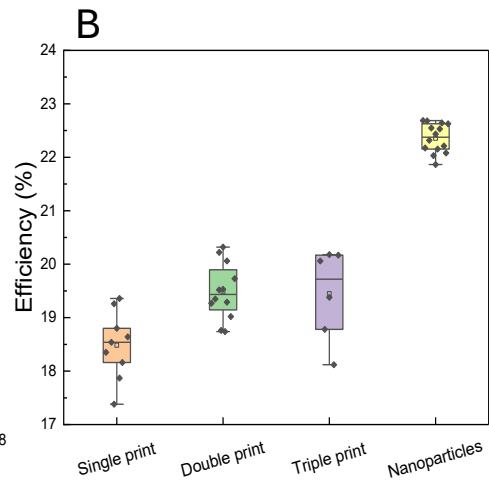
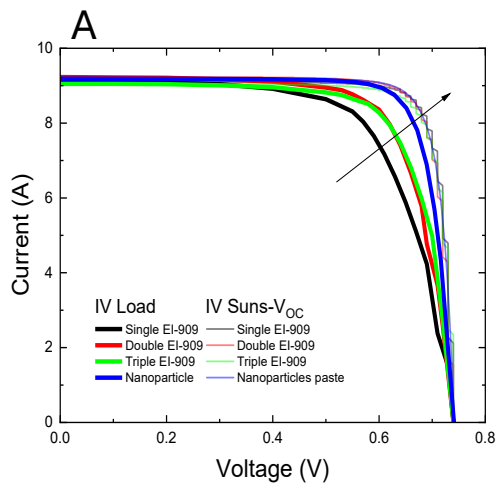
- **Single print:** often see discontinuity, inhomogeneous fingers, led to high series resistance.
- **Multiple print:** fingers are more uniform, additional prints fill up broken fingers, improve conductivity.
- **Nanoparticle paste:** uniform EL, due mainly to the well-printed fingers.

JV curves of printed devices

- Suns-Voc IV curves are all the same.
- Nanoparticle paste printed device has better fill factor, closing to the Suns-Voc curve.
- Double print and triple print show not much difference.



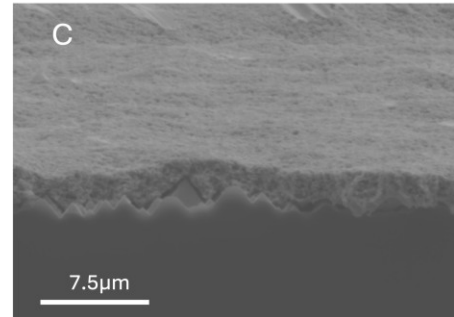
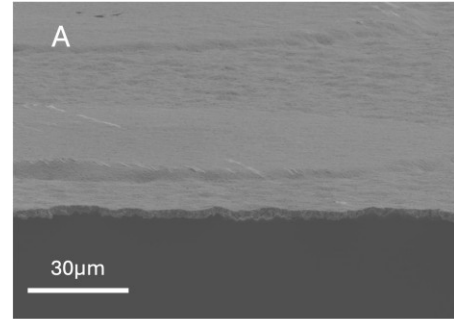
Devices performance



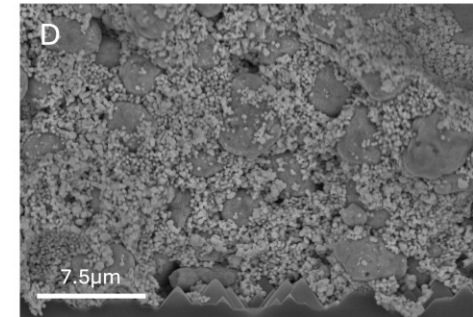
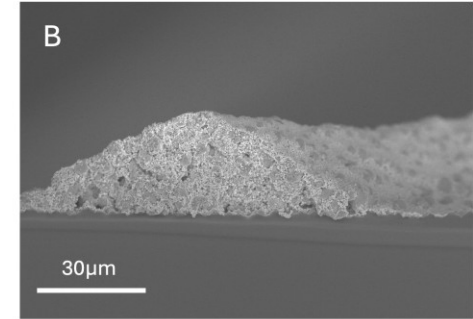
Morphology of printed fingers

- Ag complex ink:
 - Very thin 1-2 μm .
 - Denser, smaller Ag particles.
 - Less Ag.
- Ag/Cu nanoparticle paste:
 - Triangle shaped, thick $\sim 30 \mu\text{m}$.
 - Small Ag + large Cu particles.
 - Porous.

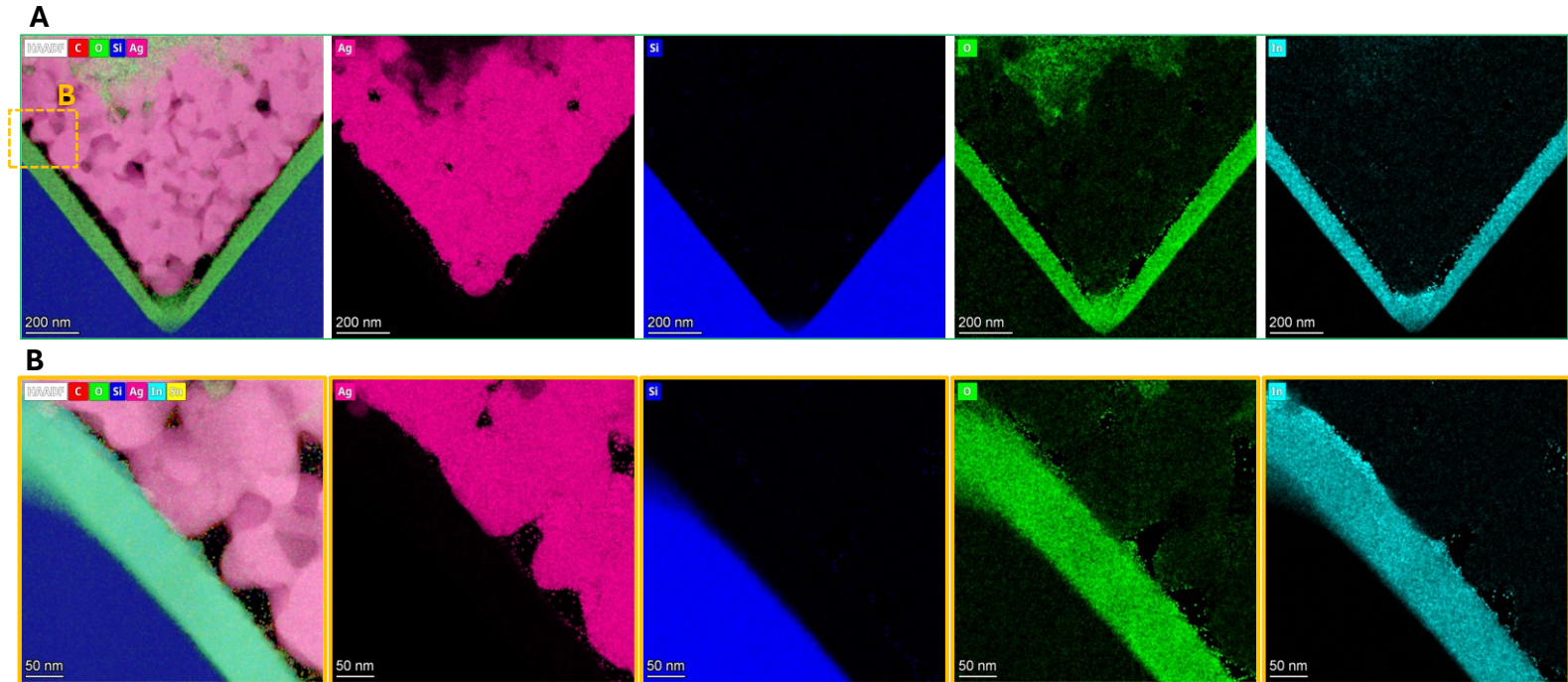
Ag complex ink



Ag/Cu nanoparticle



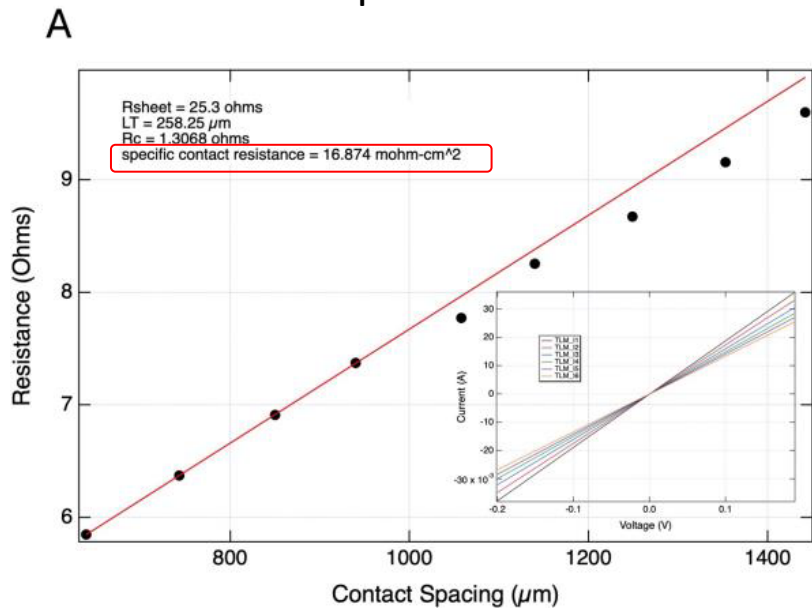
STEM images



- Gaps between Ag and ITO. Contact resistivity might not be good?
- Clear elemental maps showing interfaces between metal/ITO/aSi.

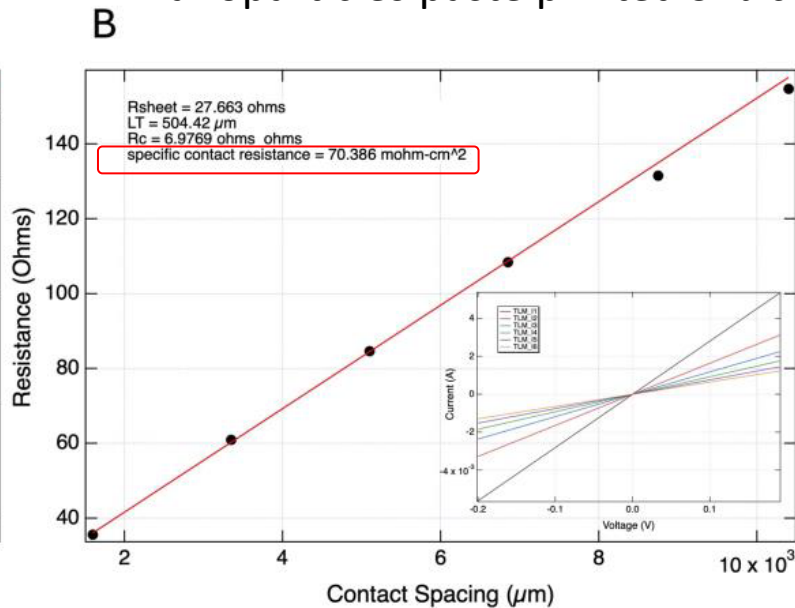
TLM of printed SHJ cells

A EI-909 printed SHJ cells



$$\rho_c \sim 17 \text{ m}\Omega\cdot\text{cm}^2$$

B nanoparticles paste printed SHJ cells



$$\rho_c \sim 70 \text{ m}\Omega\cdot\text{cm}^2$$

Contact resistivity is better than nanoparticle paste printed devices!

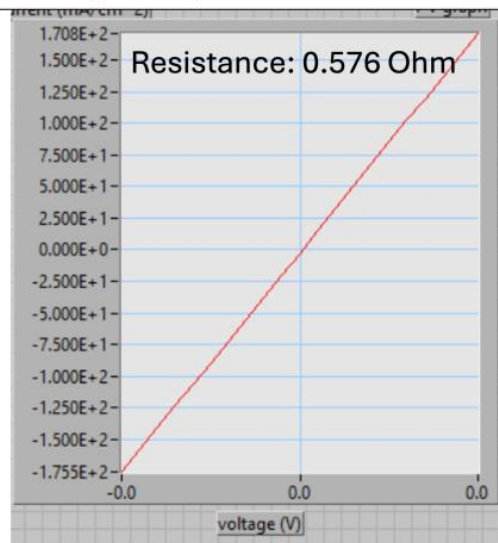
Conductivity of printed metal traces

A: EI-909

Line resistivity = $R.A/L =$

$$0.567 \times 1 \times 623 / 10000 \times 100 = 3.5 \mu\Omega \cdot \text{cm}$$

Bulk Ag: $1.58 \mu\Omega \cdot \text{cm}$

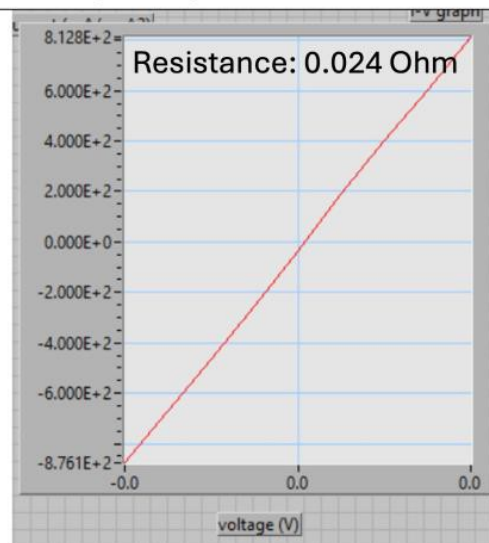


B: Nanoparticles paste

Line resistivity = $R.A/L =$

$$0.024 \times 30 \times 1000 / 15000 = 4.8 \mu\Omega \cdot \text{cm}$$

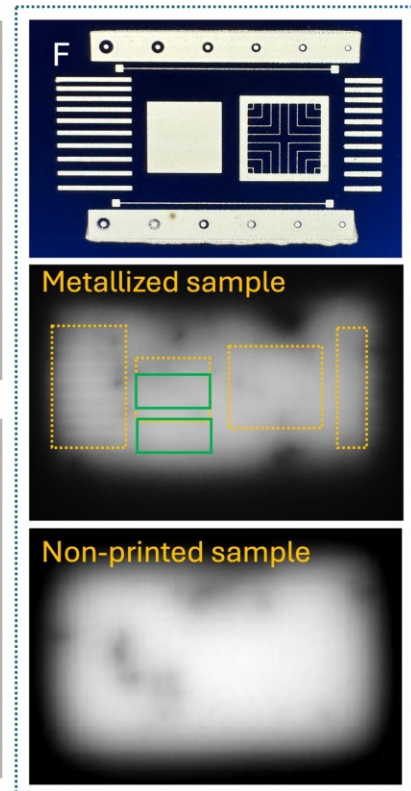
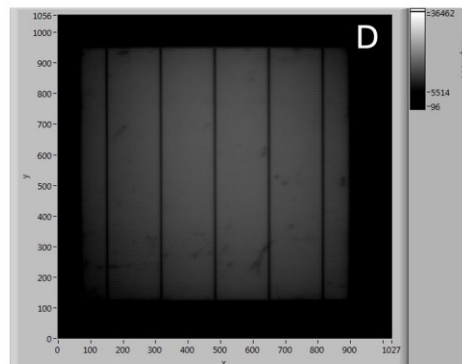
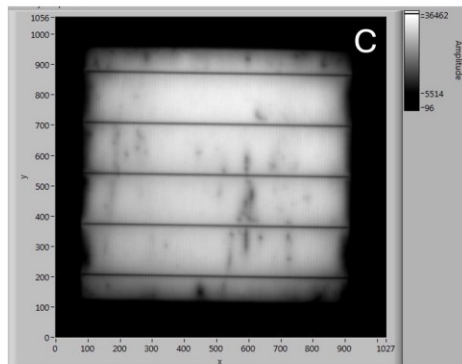
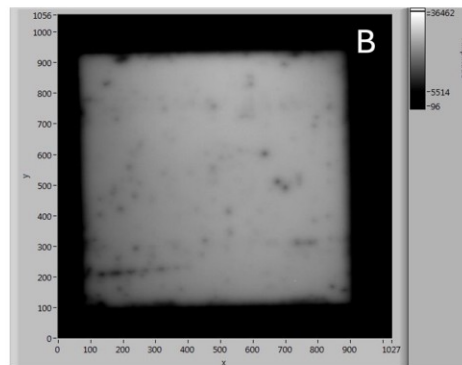
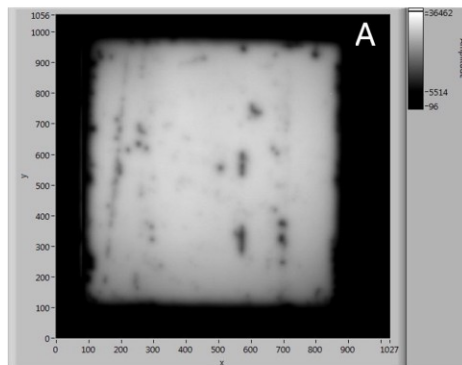
Bulk Ag: $1.58 \mu\Omega \cdot \text{cm}$



EI-909 printed fingers have better conductivity!

Photoluminescence

- Ag complex ink: PL intensity is similar before and after metallization.
- Nanoparticle paste: PL of device after annealing is darker, due to higher annealing temperature.
- $\Delta iV_{oc} < 3.5$ mV.

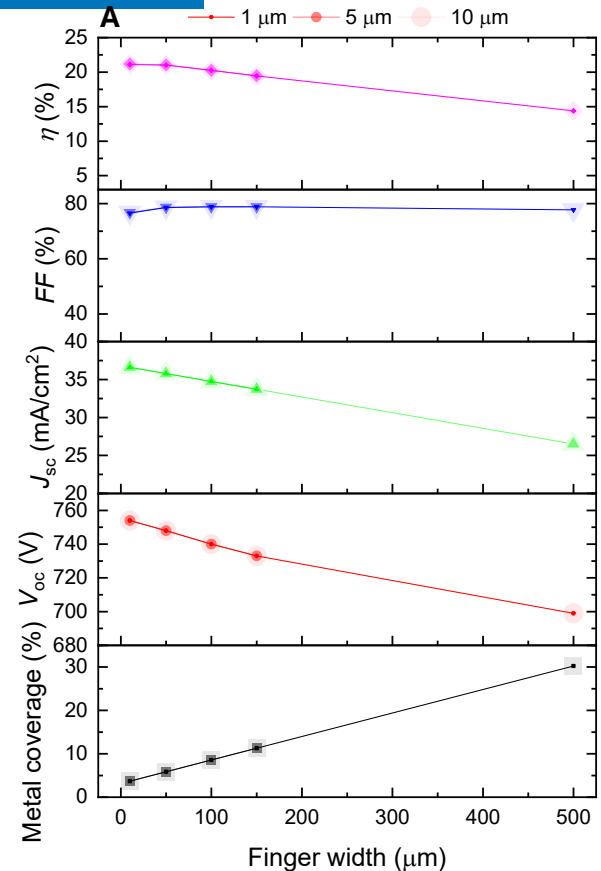


Griddler Simulation

- Arbitrary device parameters for a 21% device, varying front metal grid parameters/metal coverage.
- Varying finger width with different finger thickness show minimal changes in performance.
- Devices with multipass printing show improved performance. Why?
- This is because: multipass printing can fill in metal ink into breakups, cracks, or disruption.

Key issues with the current complex inks:

- Printability with screen printing.
- Stability studies.

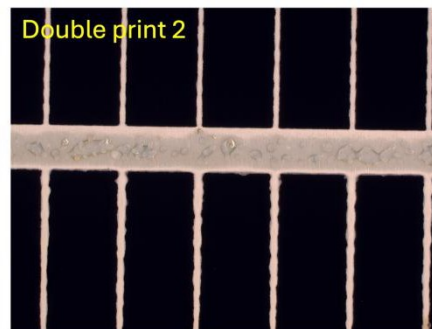
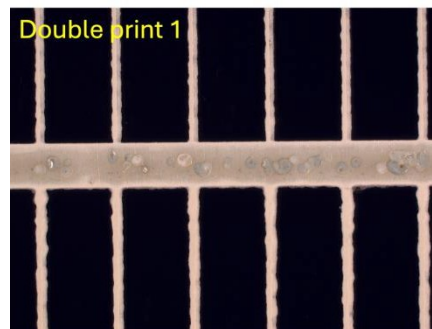
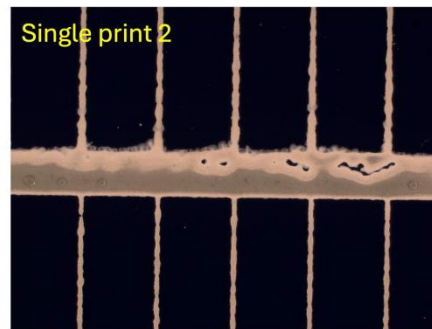
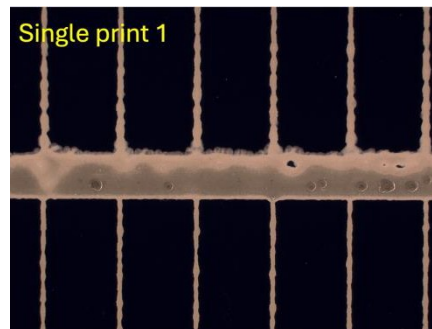


Optical images

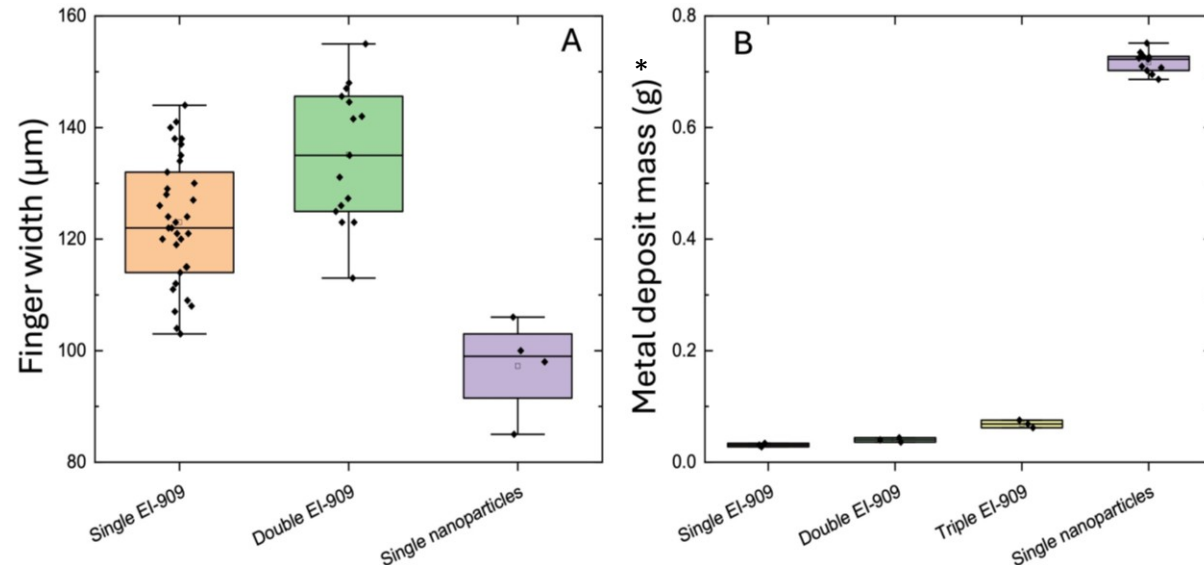
Optical images of screen-printed EI-909 ink on SHJ cells with single and double printing strategy.

Printability:

- Fingers often show necking, nonuniformities, breaks.
- Double print can fill metal ink in those defects but cause spreading, wider fingers.



Width and mass of printed features



- Multi-passes produces wider fingers, likely due to misalignment.
- For Ag complex ink: Screen: 80 μm . Printed: 100-140 μm (10-20 μm spreading).
- Metal deposit: ~ 0.03 g vs 0.73 g (including 50%wt Ag-coated Cu nanoparticle).

*On G1 wafer 158x158 mm².

Summary

First demonstration of commercial Ag complex ink EI-909 on SHJ cells using screen printing.

20% SHJ solar cells with routes to improve performance.

Needs improvement in printability with proper viscosity and thixotropy for industrial fine-line screen printing.

Significant reduction in Ag usage from ~ 0.4 g to ~ 0.03 g.

Demonstrated Ag complex inks as a viable alternative to current nanoparticle paste.

Thank you! Q&A?

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Appendix

Email Thien.Truong@nlr.gov for more details.